Z31 These assemblies are ESD sensitive. ESD precautions shall be observed.
Z32 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
Z33 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
Z34 J5 and J6, SMT-110-23-F-1, connectors are to be installed on the bottom of the PCB. This means the male leads of J5 and J6 will be visible from the top and the female from the bottom.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANTS GOD
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ASSEMBLY VARIANT: O01
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